

ABSTRACT

A laminate which comprises a thermoplastic polyimide layer and a metal layer, or comprises a non-thermoplastic polyimide film layer
5 and, formed on one or both surfaces, a thermoplastic polyimide layer and a metal layer; and a printed wiring board comprising the laminate. The laminate can be used for forming a high density circuit thereon, exhibits good resistance to further processing such as desmearing and excellent adhesion, and is excellent in adhesion reliability in a high
10 temperature atmosphere.